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measurements and tests are as follows (除另有说明外, 用以进行测量和测试的标准环境条件范围如下)

5.1 Ambient temperature(环境温度): 5°C to 35°C

5.2 Relative humidity (相对湿度): 45% to 85%

5.3 Air pressure (气压): 86Kpa to 106Kpa


6. HOWEVER, IF DOUBTS ARISE CONCERNING JUDGMENTS. PERFORM UNDER THE FOLLOWING STANDARD

CONDITIONS.(但是, 如果对判决产生疑问, 按照下列标准条件执行)

Temperature(温度): 23±1°C.

Humidity(湿度): 50%±2% RH.

Air Pressure(气压): 86~106kPa

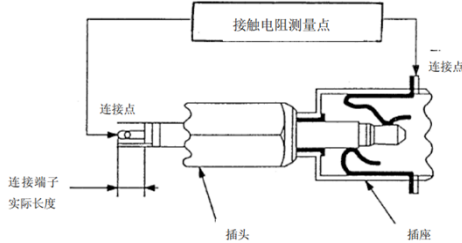
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7. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

7.1 APPRARANCE (外观)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Appearance (外观)	Visual. (目视)	Should not have any flaw Scratch discoloration and crushed (无任何裂痕、刮伤、污染和变形)


7.2 ELECTRICAL (电气)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Low level contact resistance. (接触电阻)	<p>Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max</p> <p>Test method complies with EIA-364-06C. (依EIA-364-06C, 开路电压为20mV最大, 电流为1mA最大)</p> 	<p>Contact terminals接触端子: 100 mΩ Max.</p> <p>Change of 40 mΩ Max. after testing. (测试后变化量40 mΩ Max.)</p>
2	Insulation Resistance. (绝缘电阻)	<p>After 100 VDC for 1 minute, measure the insulation resistance between the adjacent contacts of mated and unmated connector assemblies. (使用100 V交流電測試1分鐘, 測量相邻两端的绝缘电阻)</p>	100 MΩ min.
3	Dielectric strength. (耐电压)	<p>Apply ac 500V for 1minute 0.5mA between adjacent terminal or ground.</p> <p>Test method complies with EIA-364-20C (依EIA-364-20C, 相邻两端使用500 V交流电测试1分钟, 电流0.5mA)</p>	<p>Without damage to parts arcing or breakdown etc. (无短路或其他损坏)</p>

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7.3 MECHANICAL (机械)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Insertion/Extraction force. (插入/拔出力)	Measure the module insertion extraction force at 25±3mm/min. (插入拔出速度为25 ± 3mm/分钟) EIA364-13	2.2N~22.2N
2	Durability (耐久)	Number of test cycle is 5000 minimum and cycles rate is 100 ± 50 cycles per hour. (插拔周期次数最少为5000次, 周期率为100 ± 50次/小时) EIA 364-B	Contact resistance接触电阻:100 mΩ Max. Change of 40 mΩ Max. after testing. (测试后变化量40 mΩ Max.) Insulation Resistance绝缘电阻: 100 MΩ min. No physical damage to Connector shall occur. (不可对连接器造成物理损伤)
3	Contact retention force (保持力)	Apply axial pull out force on the Terminal assembled in the housing at A rate of 25±3mm min. (对组装在胶壳内的端子施加轴向拉出力, 速度至少为25 ± 3毫米)	4.9N
4	Mechanical Shock (机械冲击)	Accelerated Velocity(加速度): 50 G (490 m/s²) Waveform (波形) : Semi Sine (半正弦) Duration (持续时间) : 11 m sec. No of Shocks (冲击频率) : 6/dir., 3 axis, (6个面, 3个轴) (Total of 18 Shocks共18次冲击) EIA364-27	(1) contact Resistance接触电阻: 100 mΩ Max . (2) contact Resistance绝缘电阻: 500 MΩ MIN . (3) No electrical discontinuity greater than 100nsec. shall occur (电气连续性不超过100秒)
5	Vibration (振动)	Frequency Range(频率范围): 10-2000 Total Amplitude(总振幅):2m/s². Duration(时间): 2.5 hours 3 axes IEC 60512-6-4	(1) contact Resistance接触电阻: 100 mΩ Max . (2) contact Resistance绝缘电阻: 500 MΩ MIN . (3) No electrical discontinuity greater than 100nsec. shall occur (电气连续性不超过100秒)

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7.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	High Temperature (高温)	<p>The contact and card is exposed in the heat chamber 90°C for 96 hours. After test stored at room temperature for 1 hours test CR and IR. (触点和卡片在90 ° c 的热室中暴露96小时, 测试后放置室温1小时测试接触电阻与绝缘阻抗) IEC 60512-11-3</p>	<p>(1) contact Resistance接触电阻: 100 mΩ Max . (2) contact Resistance绝缘电阻: 500 MΩ MIN . □2□ Shall occur Function and performance shall be as specified. Not to change for physical appearance. (功能各外观须正常, 不得有任何损坏)</p>
2	Low Temperature (低温)	<p>The contact and card is exposed in the cold chamber -25°C for 96 hours. After test stored at room temperature for 1 hours test CR and IR. (触点和卡片在-25° c 的冷室中暴露96小时, 测试后放置室温1小时测试接触电阻与绝缘阻抗) IEC 60512-11-3</p>	<p>(1) contact Resistance接触电阻: 100 mΩ Max . (2) contact Resistance绝缘电阻: 500 MΩ MIN . (3) Shall occur Function and performance shall be as specified. Not to change for physical appearance. (功能各外观须正常, 不得有任何损坏)</p>
3	Humidity resistance (高湿)	<p>Steady state 40°C,90~95%RH for 96H with mate connectors , After test stored at room temperature for 1 hours test CR and IR. (配对连接器在40° C 90~95%RH的稳定状态下测试96小时, 测试后放置室温1小时测试接触阻抗与绝缘阻抗) IEC 60512-11-3</p>	<p>(1) contact Resistance接触电阻: 100 mΩ Max . (2) contact Resistance绝缘电阻: 500 MΩ MIN . (3) Shall occur Function and performance shall be as specified. Not to change for physical appearance. (功能各外观须正常, 不得有任何损坏)</p>

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4	XKB Connectivity Salt Spray Test (盐雾测试)	<p>Mated connectors to 35+/- 2°C. Humidity: 85% (R.H). PH value: 6.5~7.2 and 5+/-1% salt condition for 24 hours. After test, rinse the sample with water and recondition the room temperature for 1 hour test CR and IR.</p> <p>(配对连接器放置在 35±2°C, 温度为 85% PH 值 6.5~7.2 和 5% 浓度的实验箱内测试 24 小时, 测试后用水清洗样品, 放置室温 1 小时测试接触阻抗与绝缘阻抗) EIA-364-26B.</p>	<p>(1) contact Resistance 接触电阻: 100 mΩ Max .</p> <p>(2) contact Resistance 绝缘电阻: 500 MΩ MIN .</p> <p>(3) Appearance shall no rust, oxidation, corrosion and other undesirable phenomena. (外观须无生锈、氧化、腐蚀等不良现象)</p>
5	Solder ability (沾锡性)	<p>Solder Temperature (焊接温度): 245+/- 3°C</p> <p>Immersion Duration (浸泡时间): 3 ±0.5 sec.</p> <p>Flux (助焊剂): RMA 25%</p>	<p>Wet Solder Coverage: 95 % Min. (沾锡面积须 95% 最小)</p>
6	Resistance to soldering heat (焊锡耐热性)	<p>The contact of terminal shall be tested resistance to soldering heat in the following conditions. After Resistance to soldering heat test Contact Resistance. (端子应在下列条件下做耐吃锡性试验, 焊锡耐热性后试接触阻抗)</p> <p>In case of solder iron (2 time) 电烙铁(两次)</p> <p>Temperature 温度: ≤350°C</p> <p>Time 时间: 5s+/-1s</p>	<p>Should not have any flaw scratch and crack. (无任何裂痕、刮伤和破裂)</p>
7	IR-reflow (回流焊)	<p>MIL-STD-202G method 210F</p> <p>Peak temperature time 260°C Max, 10 sec or more. (峰值温度时间最高 260°C, 10 秒或更长的时间)</p> <p>Duration: 2 cycles (过炉 2 次)</p> <p>Lead-Free Solder (无铅锡膏): Sn96.5Ag3Cu0.5</p> <p>Refer to section 8.0 (请参阅第 8.0 条)</p>	<p>Should not have any flaw scratch and crack (无任何裂痕、刮伤和破裂)</p> <p>No visual damage to insulator. (绝缘体不得有严重变形)</p>

8. Product Qualification and TEST GROUP (产品验证和测试分组)

XKB Connectivity TEST ITEM (测试项目)	TEST GROUP (测试分组)										
	A	B	C	D	E	F	G	H	I	J	K



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		TEST SEQUENCE										
1	Appearance (外观)	1,4	1,7	1,6	1,3	1,6	1,7	1,5	1,5	1,5	1,4	1,4
2	Low Level Contact Resistance (接触电阻)		3,6	3,7			3,8	3,6	3,6	3,6		2,5
3	Dielectric withstanding Voltage (耐电压)					4,8	5,9					
4	Insulation Resistance (绝缘电阻)					3,7	4,10					
5	Temperature Rising (升温)	3										
6	Durability (耐久)		5									
7	Vibration (振动)			4								
8	Mechanical Shock (机械冲击)			5								
9	Insertion/Extraction force (插入/拔出力)		4									
10	Contact retention force (保持力)				2							
11	High Temperature (高温)					5						
12	Low Temperature (低温)						6					
13	Humidity resistance (高湿)							4				
14	Salt Spray (盐雾)								4			
15	Solder ability (沾锡性)										3	
16	Reflow Soldering Heat Resistance (焊锡耐热性)											3
17	IR-reflow (回流焊)	2	2	2		2	2	2	2	2	2	
	Number of Samples Required (所需样本数目)	5										

9. WAVE SOLDERING (波峰焊)

DIP Suggestions solder temperature at 235°C±5°C(455°F) max.5 seconds . (DIP型推荐焊接焊锡温度为235°C±5°C(455°F) 最多5秒)

10. REFLOW PROFILE (XKB CONNECTIVITY 回流焊炉温图)

260°C maximum (Peak Temperature)



